

**Amendments to the Specification:**

Please replace the paragraph, beginning at page 2, line 23, with the following rewritten paragraph:

Another nanostructure manufacturing process is ~~referred~~ referred to in the art as nanoimprinting or nanoimprint lithography, which involves compressive patterning of deformable films coated on a substrate by way of a mold having protrusions and recesses. See for example, U.S. Pat. Nos. 5,772,905 and 6,309,580. The thickness of the film under the protruding feature is thinner than the thickness of the film under the recess. Thus, a relief is formed in the thin film. The relief conforms the mold's features. The relief is processed such that the thinner portion of the film is removed thereby exposing the underlying substrate in a pattern complementary to the mold. The relief patterns so produced can be reproduced in the substrate or in another material.

Please replace the paragraph, beginning at page 11, line 9, with the following rewritten paragraph:

As used herein, the term "photocurable" is meant to refer to compositions in which a chemical reaction is brought about upon the application of a photon, such as light, e.g., ultraviolet ("UV") light. Suitable photocurable compositions typically include at least one monomer and one photocuring agent. Any one monomer, or combination of monomers, as herein described may be suitably used. Suitable photocuring agents include polymerization initiators, cross-linkers and graft-linkers that are activated by radiation, typically ultraviolet light. Suitable photocurable polymeric compositions will typically cure upon the exposure of radiation within the range of about 1 millisecond to about 2 seconds, although curing times are envisioned as capable of being outside this range. Suitable photocurable polymeric compositions have viscosities typically greater than 100 centipoise (cps), although viscosities are envisioned as capable of being outside this range. The photocurable polymeric compositions also desirable have suitably

low energy of adhesions to the mold surfaces to provide ready release of the cured nanoimprint resist from the mold. Suitably low energy of adhesions can be provided by choosing polymeric compositions that have relatively low interaction energies for the mold surfaces, for example by the inclusion of silicon-containing or fluorine-containing components in the polymeric composition. This can be suitably provide by selecting suitable components of the polymeric composition, e.g. polymer, monomer, oligomer, and photocuring agent that provide low energies of adhesion. More typically, an internal mold release agent is included in the polymeric compositions. Examples of internal mold release agents are provided herein. An examples of a suitable photocuring agents includes IRGACURE 184. When a crosslinking agent ("cross-linker") is included in the polymeric compositions, the polymeric compositions typically crosslink in less than about 2 seconds. Desirable photocurable polymeric compositions are capable of crosslinking in the presence of oxygen.

Please replace the paragraph, beginning at page 20, line 6, with the following rewritten paragraph:

A composition of the invention comprises the following components.

Component	weight percent
Acrylic polysiloxane	73%
<u>Trimethylolpropane triacrylate (TMPTA)</u>	11%
Laurylmethacrylate	12%
<u>IRGACURE Irgacure184</u>	4%